

## DESCRIPTION

The MX4408 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

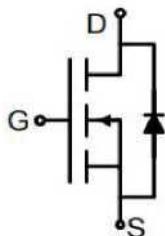
## GENERAL FEATURES

- $V_{DS}=30V$ ,  $I_D=13A$
- $R_{DS(ON)}(\text{Typ.})=10\text{m}\Omega$  @  $V_{GS}=4.5V$
- $R_{DS(ON)}(\text{Typ.})=7\text{m}\Omega$  @  $V_{GS}=10V$
- High density cell design for ultra low Rdson
- Lead free product is acquired

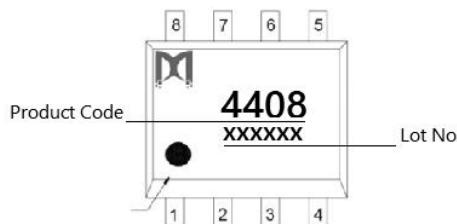
## APPLICATION

- Battery protection
- Load switch
- Power management

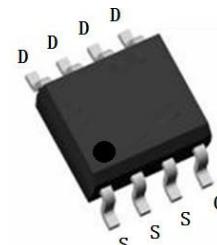
## PINOUT



Schematic diagram



Marking and pin Assignment



SOP-8 top view

## ORDERING INFORMATION

Part Number	Marking	Storage Temperature	Package	Devices Per Reel
MX4408	4408	-55°C to 150°C	SOP-8	3000

## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage ( $V_{GS}=0V$ )	$V_{DS}$	30	V
Gate-Source Voltage ( $V_{DS}=0V$ )	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^\circ C$ ) <sup>(Note 1)</sup>	$I_D$	13	A
Drain Current-Continuous ( $T_C=100^\circ C$ )	$I_D$	7	A
Drain Current-Continuous@ Current-Pulsed <sup>(Note 2)</sup>	$I_{DM(\text{pulse})}$	44	A
Maximum Power Dissipation	$P_D$	3	W
Avalanche Energy <sup>(Note 3)</sup>	$E_{AS}$	90	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

## THERMAL RESISTANCE

Parameter	Symbol	Max.	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	42	°C/W

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition:  $T_J=25^\circ C$ ,  $V_{DD}=30V$ ,  $V_G=10V$ ,  $R_G=25\Omega$ ,


**ELECTRICAL CHARACTERISTICS**( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
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**On/Off Characteristics**

Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6\text{A}$	-	10	12	$\text{m}\Omega$
		$V_{\text{GS}}=10\text{V}, I_{\text{D}}=11\text{A}$	-	7	9	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=11\text{A}$	-	12	-	S

**Dynamic Characteristics**

Gate resistance	$R_g$	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	1.2	-	$\Omega$
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	1050	-	pF
Output Capacitance	$C_{\text{oss}}$		-	214	-	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	148	-	pF
Total Gate Charge	$Q_g$	$V_{\text{DS}}=25\text{V}, I_{\text{D}}=11\text{A}, V_{\text{GS}}=10\text{V}$	-	25	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	2.5	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	9	-	nC

**Switching Characteristics**

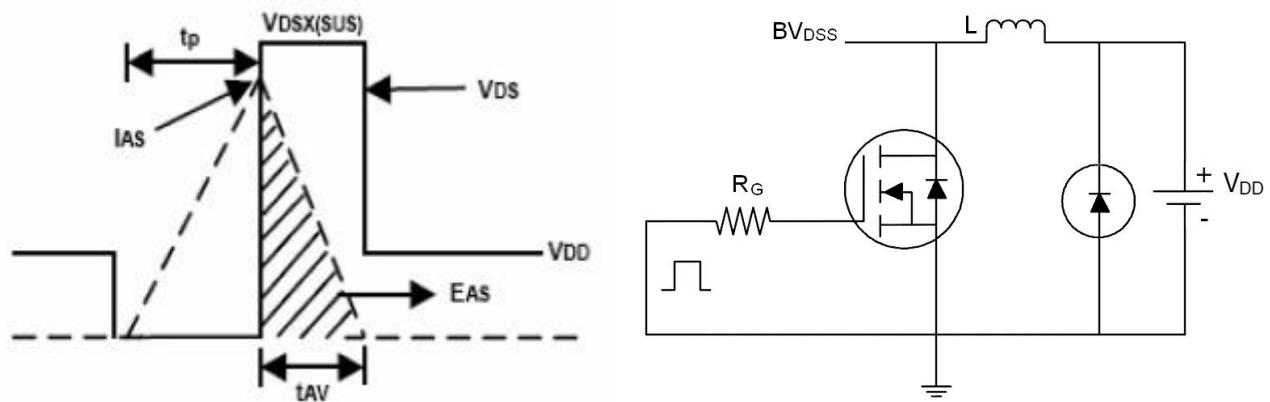
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DS}}=15\text{V}, R_L=0.75\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=3\Omega$	-	5	-	nS
Turn-on Rise Time	$t_r$		-	10	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	18	-	nS
Turn-Off Fall Time	$t_f$		-	6	-	nS

**Source-Drain Diode Characteristics**

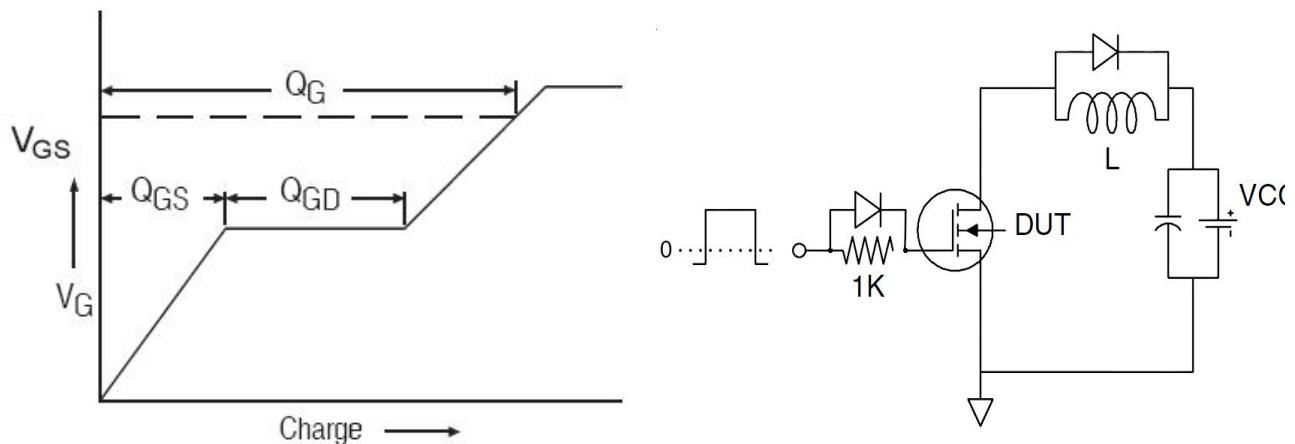
Forward On Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=11\text{A}$	-	-	1.2	V
Source-Drain Current(Body Diode)	$I_{\text{SD}}$		-	-	13	A

## TYPICAL PERFORMANCE CHARACTERISTICS

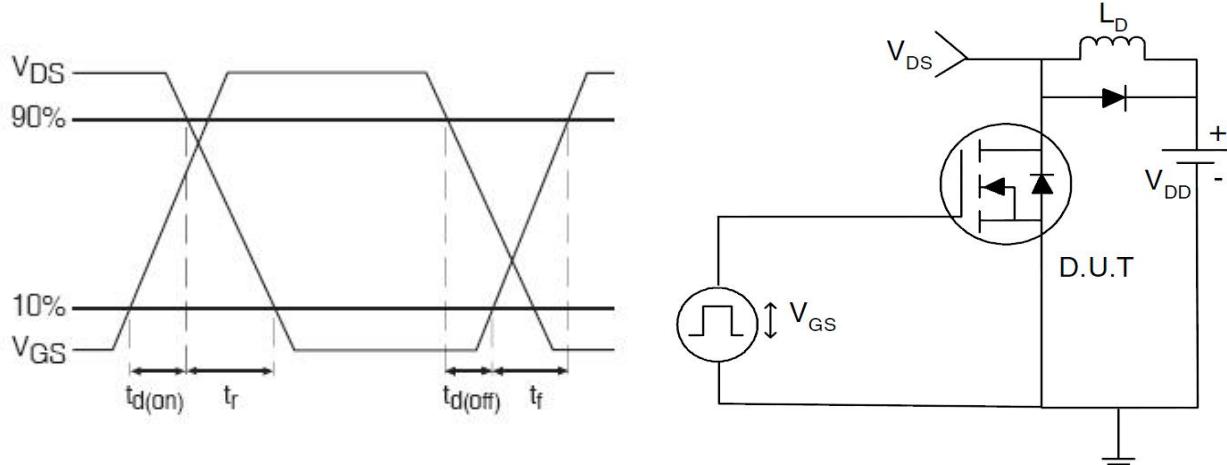
### 1) E<sub>AS</sub> Test Circuits



### 2) Gate Charge Test Circuit:

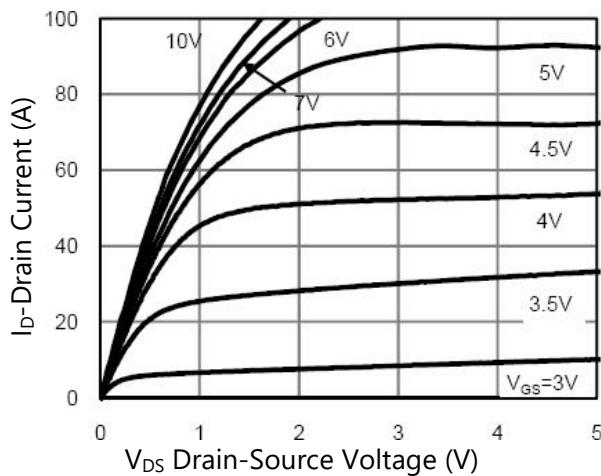


### 3) Switch Time Test Circuit:

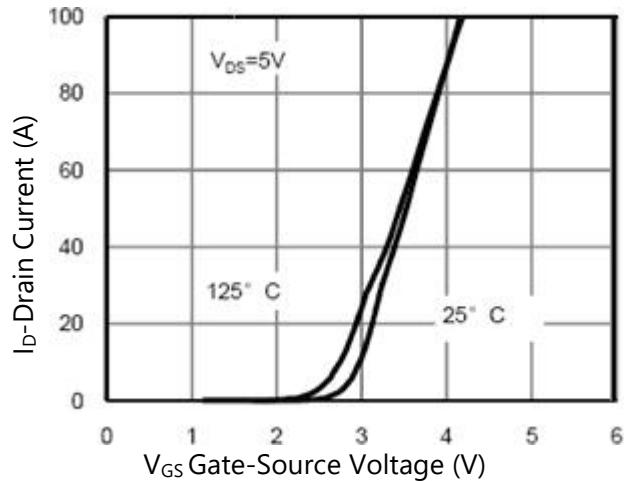


## TYPICAL PERFORMANCE CHARACTERISTICS

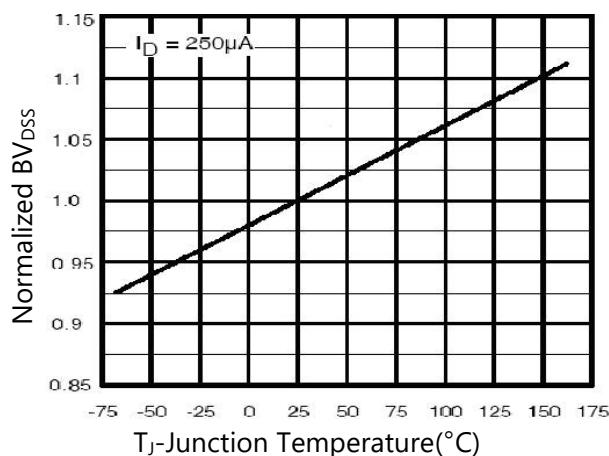
**Figure1. Output Characteristics**



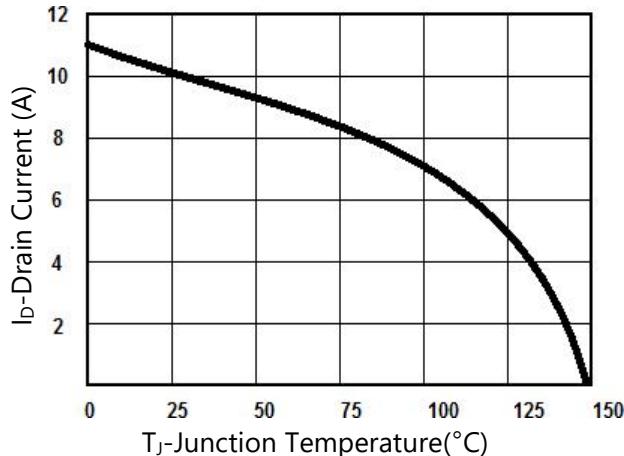
**Figure2. Transfer Characteristics**



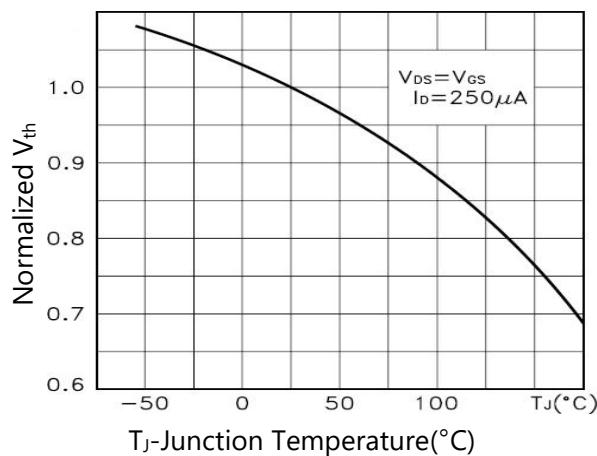
**Figure3.  $BV_{DSS}$  vs Junction Temperature**



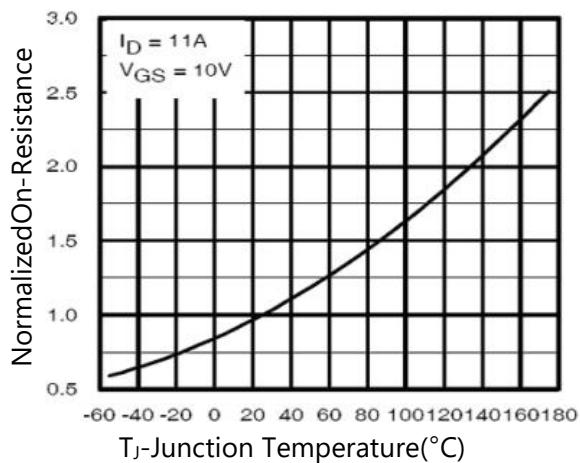
**Figure4. Drain Current**



**Figure5.  $V_{GS(th)}$  vs Junction Temperature**

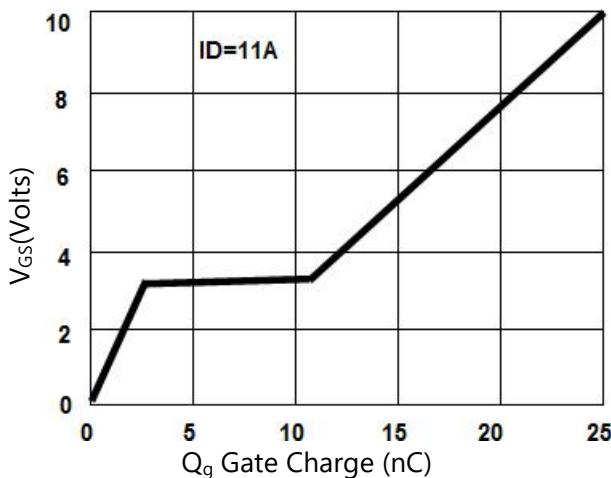


**Figure6.  $R_{ds(on)}$  Vs Junction Temperature**

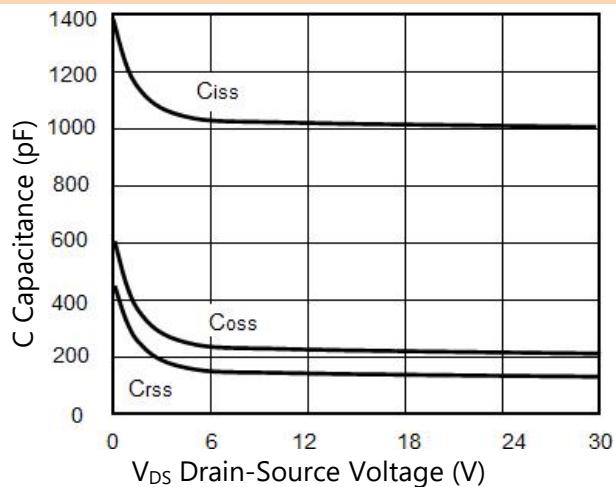


## TYPICAL PERFORMANCE CHARACTERISTICS

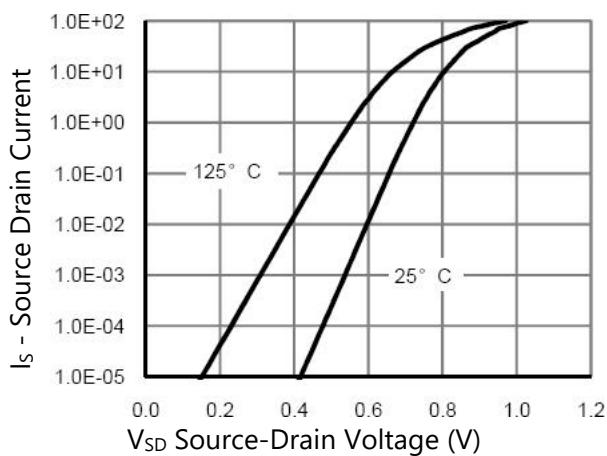
**Figure7. Gate Charge**



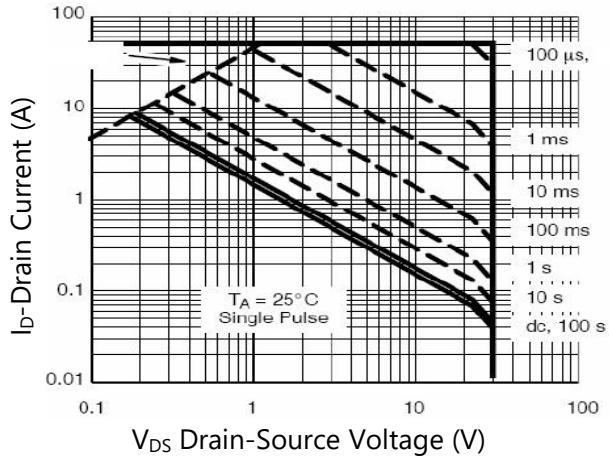
**Figure8. Capacitance**



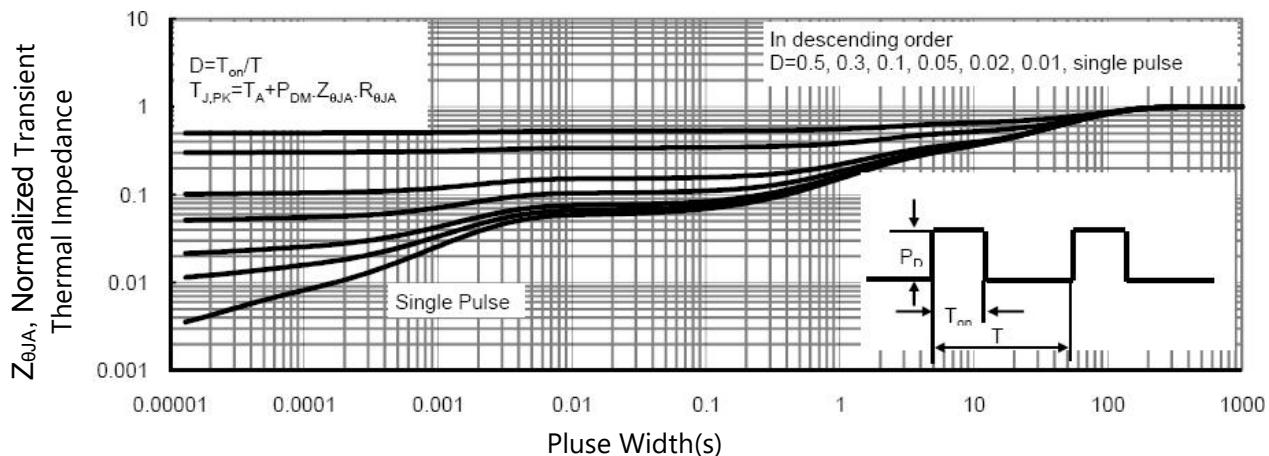
**Figure9. Body-Diode Characteristics**



**Figure10. Safe Operation Area**

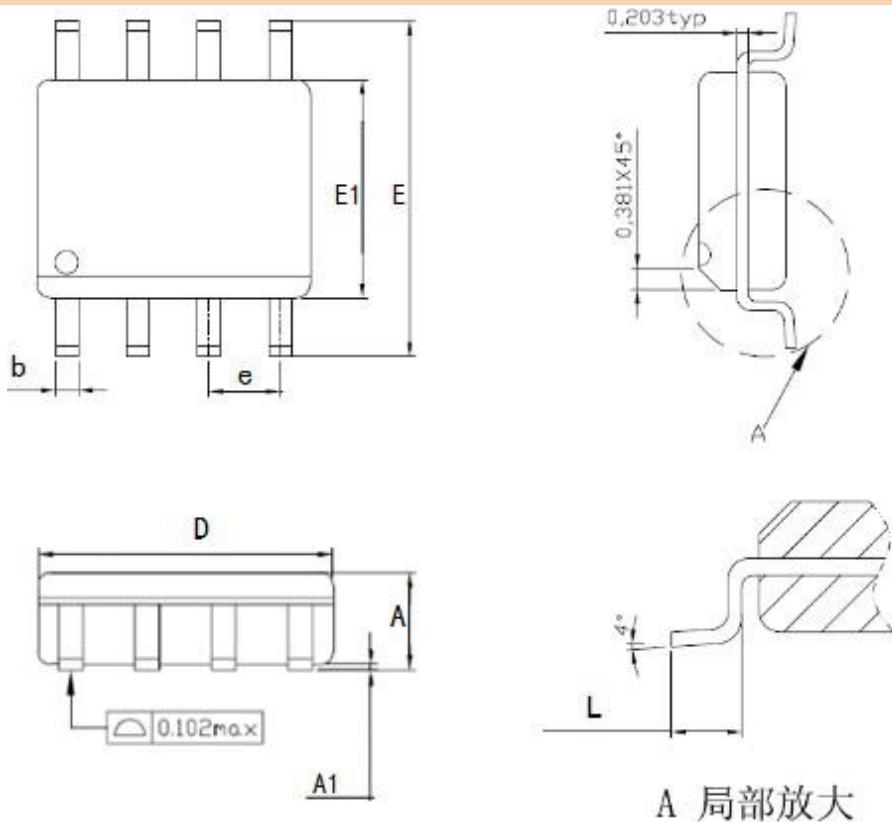


**Figure11. Normalized Maximum Transient Thermal Impedance**



## PACKAGE INFORMATION

### SOP-8



A 局部放大

Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	1.35	1.55	1.75
A1	0.1	0.15	0.2
b	0.346	0.406	0.466
D	4.8	4.89	4.98
E	5.75	6.00	6.25
E1	3.81	3.90	3.99
e	1.27 TYP		
L	0.106	0.838	1.27